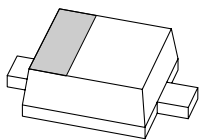




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BAT54J

Schottky barrier single diode

Rev. 01 — 8 March 2007

Product data sheet

1. Product profile

1.1 General description

Planar Schottky barrier single diode with an integrated guard ring for stress protection, encapsulated in a SOD323F (SC-90) very small and flat lead Surface-Mounted Device (SMD) plastic package.

1.2 Features

- Low forward voltage
- Very small and flat lead SMD plastic package
- Low capacitance
- Flat leads: excellent coplanarity and improved thermal behavior

1.3 Applications

- Voltage clamping
- Line termination
- Reverse polarity protection

1.4 Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
I_F	forward current		-	-	200	mA
V_R	reverse voltage		-	-	30	V
V_F	forward voltage	$I_F = 1 \text{ mA}$	^[1] -	-	320	mV

[1] Pulse test: $t_p \leq 300 \mu\text{s}$; $\delta \leq 0.02$.

2. Pinning information

Table 2. Pinning

Pin	Description	Simplified outline	Symbol
1	cathode		
2	anode		

sym001

[1] The marking bar indicates the cathode.

3. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
BAT54J	SC-90	plastic surface-mounted package; 2 leads	SOD323F

4. Marking

Table 4. Marking codes

Type number	Marking code
BAT54J	AP

5. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V_R	reverse voltage		-	30	V
I_F	forward current		-	200	mA
I_{FRM}	repetitive peak forward current	$t_p \leq 1$ s; $\delta \leq 0.5$	-	300	mA
I_{FSM}	non-repetitive peak forward current	square wave; $t_p < 10$ ms	-	600	mA
P_{tot}	total power dissipation	$T_{amb} \leq 25$ °C	[1] -	550	mW
T_j	junction temperature		-	150	°C
T_{amb}	ambient temperature		-65	+150	°C
T_{stg}	storage temperature		-65	+150	°C

[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated, mounting pad for cathode 1 cm².

6. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1][2]	-	230	K/W
$R_{th(j-sp)}$	thermal resistance from junction to solder point		[3]	-	55	K/W

[1] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm².

[2] Reflow soldering is the only recommended soldering method.

[3] Soldering point of cathode tab.

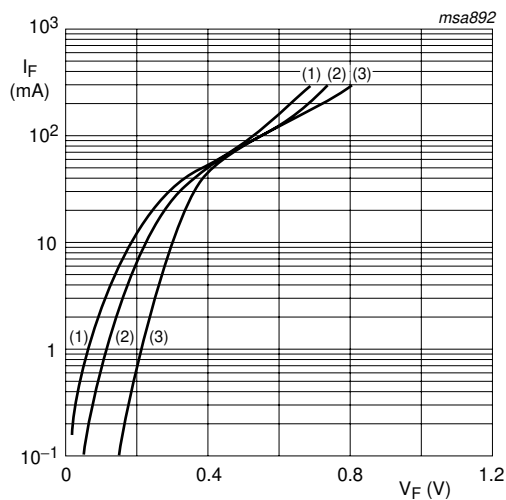
7. Characteristics

Table 7. Characteristics

$T_{amb} = 25\text{ }^{\circ}\text{C}$ unless otherwise specified.

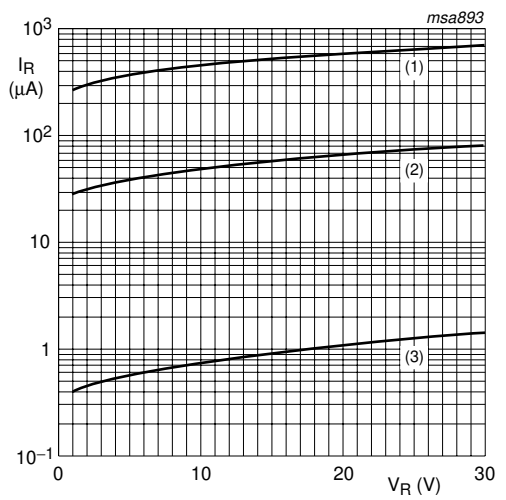
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_F	forward voltage		[1]			
		$I_F = 0.1\text{ mA}$	-	-	240	mV
		$I_F = 1\text{ mA}$	-	-	320	mV
		$I_F = 10\text{ mA}$	-	-	400	mV
		$I_F = 30\text{ mA}$	-	-	500	mV
		$I_F = 100\text{ mA}$	-	-	800	mV
I_R	reverse current	$V_R = 25\text{ V}$	-	-	2	μA
C_d	diode capacitance	$V_R = 1\text{ V}; f = 1\text{ MHz}$	-	-	10	pF

[1] Pulse test: $t_p \leq 300\text{ }\mu\text{s}$; $\delta \leq 0.02$.



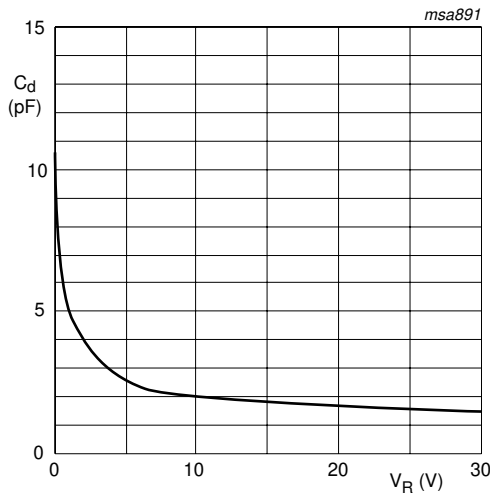
- (1) $T_{amb} = 125\text{ }^{\circ}\text{C}$
- (2) $T_{amb} = 85\text{ }^{\circ}\text{C}$
- (3) $T_{amb} = 25\text{ }^{\circ}\text{C}$

Fig 1. Forward current as a function of forward voltage; typical values



- (1) $T_{amb} = 125\text{ }^{\circ}\text{C}$
- (2) $T_{amb} = 85\text{ }^{\circ}\text{C}$
- (3) $T_{amb} = 25\text{ }^{\circ}\text{C}$

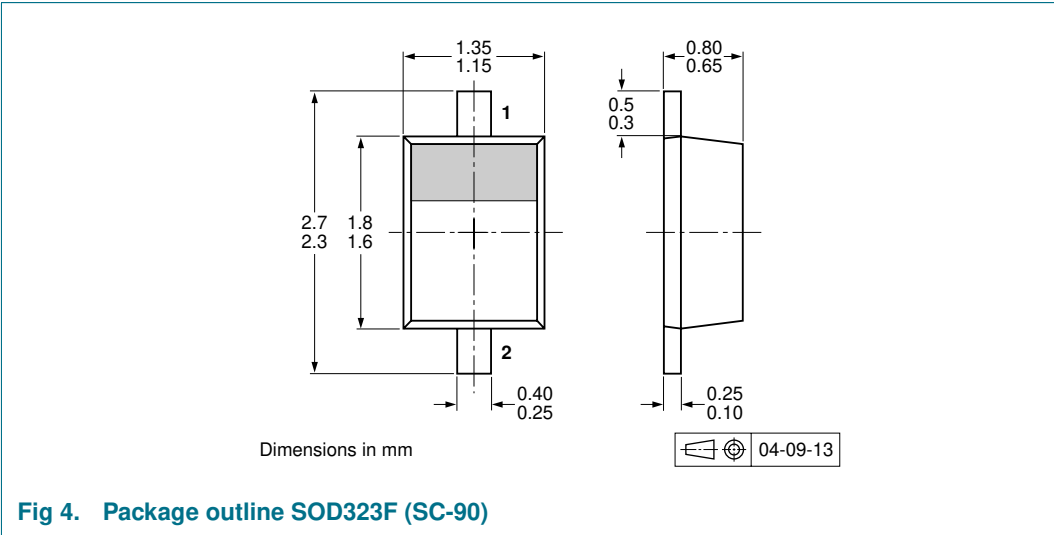
Fig 2. Reverse current as a function of reverse voltage; typical values



$T_{amb} = 25\text{ }^{\circ}\text{C}$; $f = 1\text{ MHz}$

Fig 3. Diode capacitance as a function of reverse voltage; typical values

8. Package outline



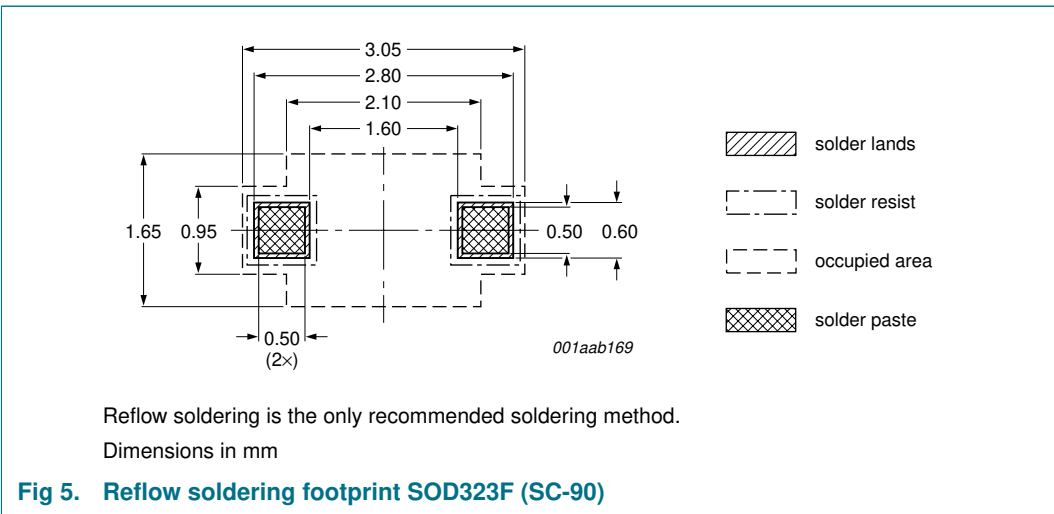
9. Packing information

Table 8. Packing methods
The indicated -xxx are the last three digits of the 12NC ordering code.^[1]

Type number	Package	Description	Packing quantity	
			3000	10000
BAT54J	SOD323F	4 mm pitch, 8 mm tape and reel	-115	-135

[1] For further information and the availability of packing methods, see [Section 13](#).

10. Soldering



11. Revision history

Table 9. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
BAT54J_1	20070308	Product data sheet	-	-

12. Legal information

12.1 Data sheet status

Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL <http://www.nxp.com>.

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14. Contents

1 Product profile 1

1.1 General description..... 1

1.2 Features 1

1.3 Applications 1

1.4 Quick reference data..... 1

2 Pinning information..... 2

3 Ordering information..... 2

4 Marking 2

5 Limiting values..... 2

6 Thermal characteristics..... 3

7 Characteristics..... 3

8 Package outline 5

9 Packing information..... 5

10 Soldering 5

11 Revision history..... 6

12 Legal information..... 7

12.1 Data sheet status 7

12.2 Definitions..... 7

12.3 Disclaimers..... 7

12.4 Trademarks..... 7

13 Contact information..... 7

14 Contents 8



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